

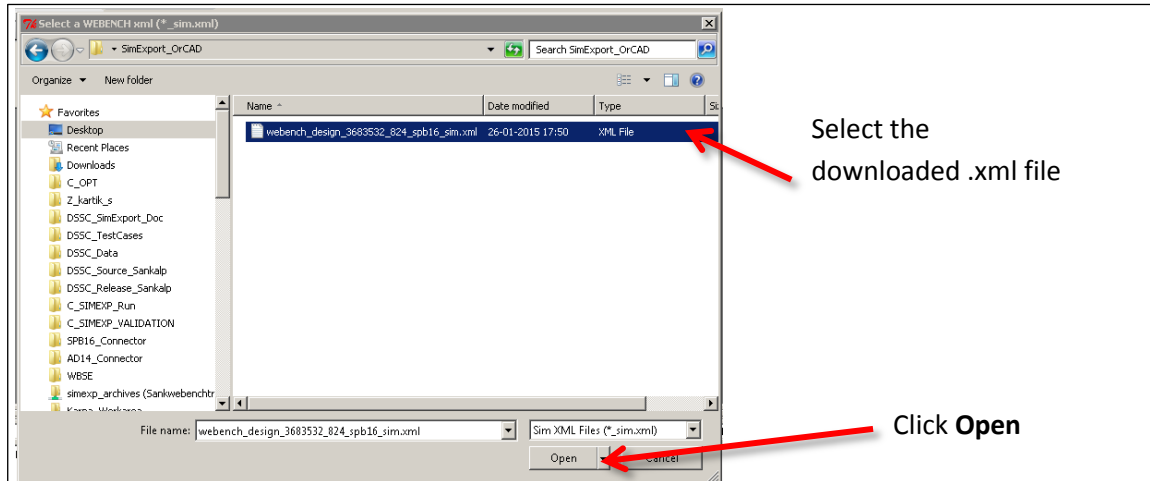
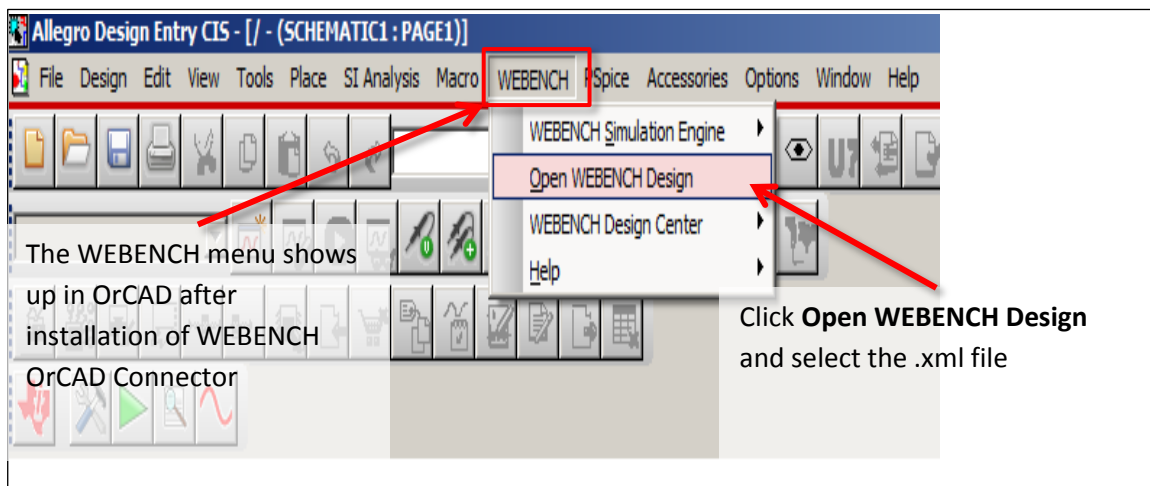


WEBENCH® Designs to OrCAD Export

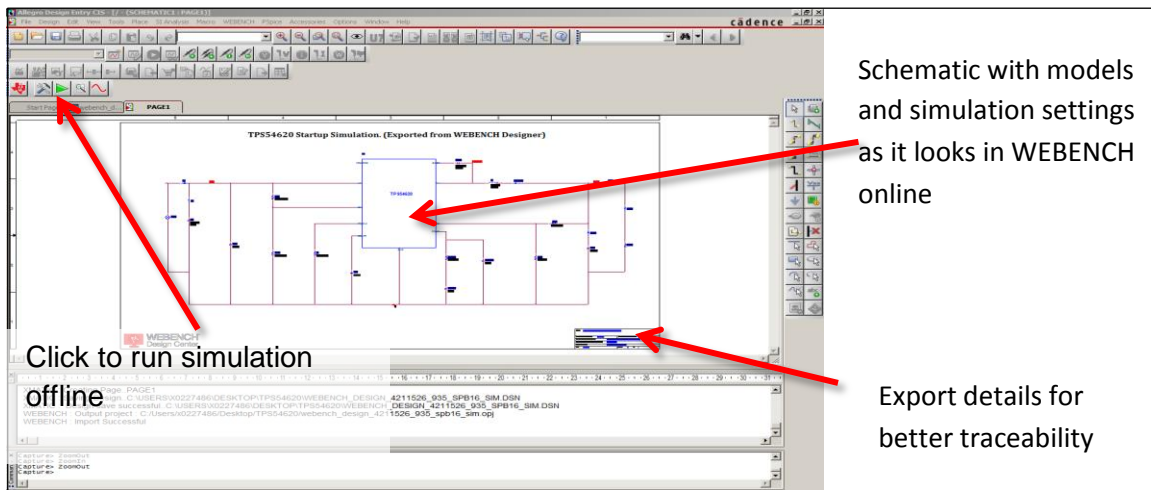
Steps to use the exported design

Note: Please install SPB 16.6 or higher, OrCAD; and WEBENCH Allegro Connector and activate it before this step.

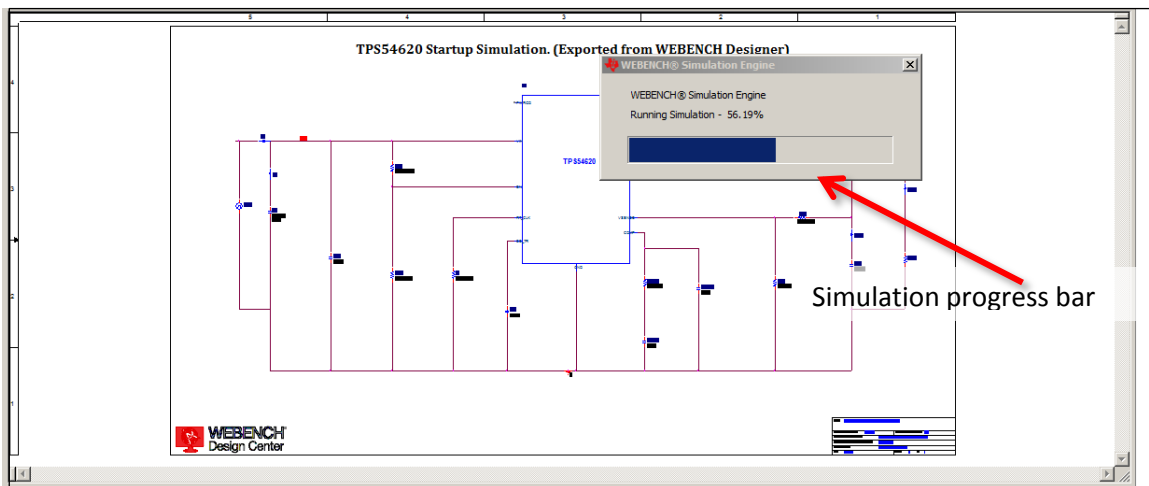
1. Start OrCAD Capture CIS (SPB 16.6). Click on the WEBENCH menu and choose **Open WEBENCH Design**



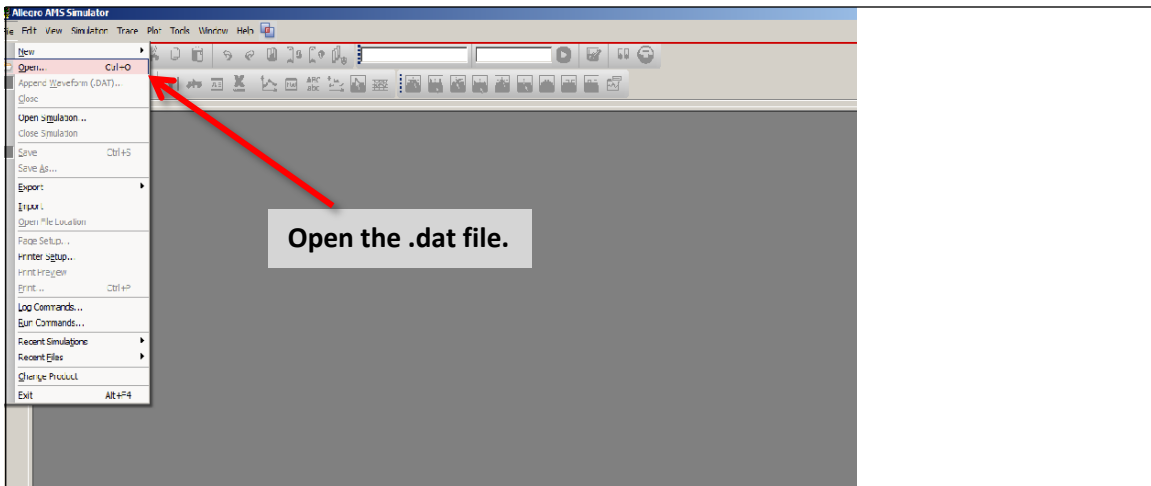
- Once opened you will see your schematic in OrCAD the same as it appears in WEBENCH online. The files include models and simulation settings. Click on the **Run WEBENCH Simulation Engine** toolbar icon to launch simulation.



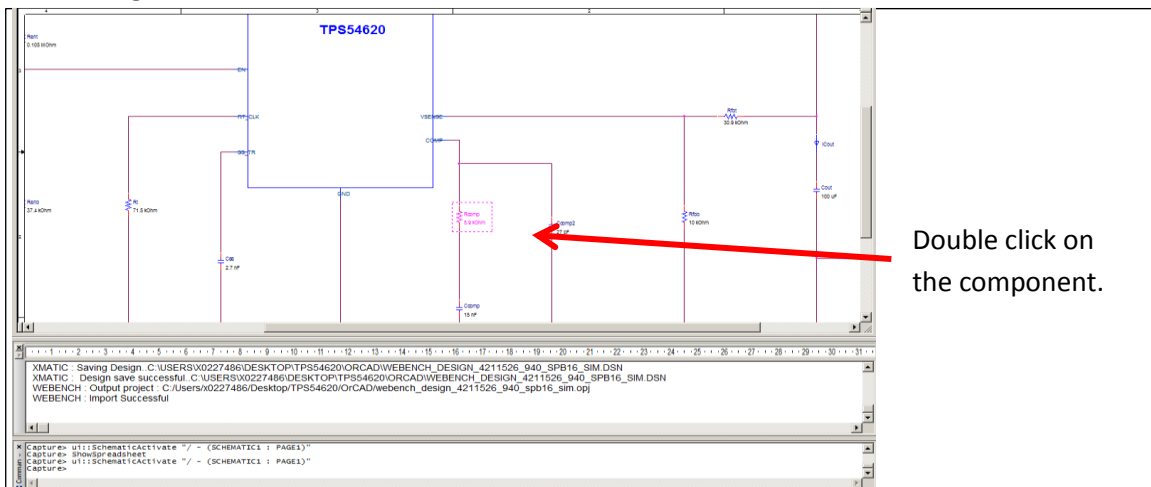
- The simulation progress bar appears.

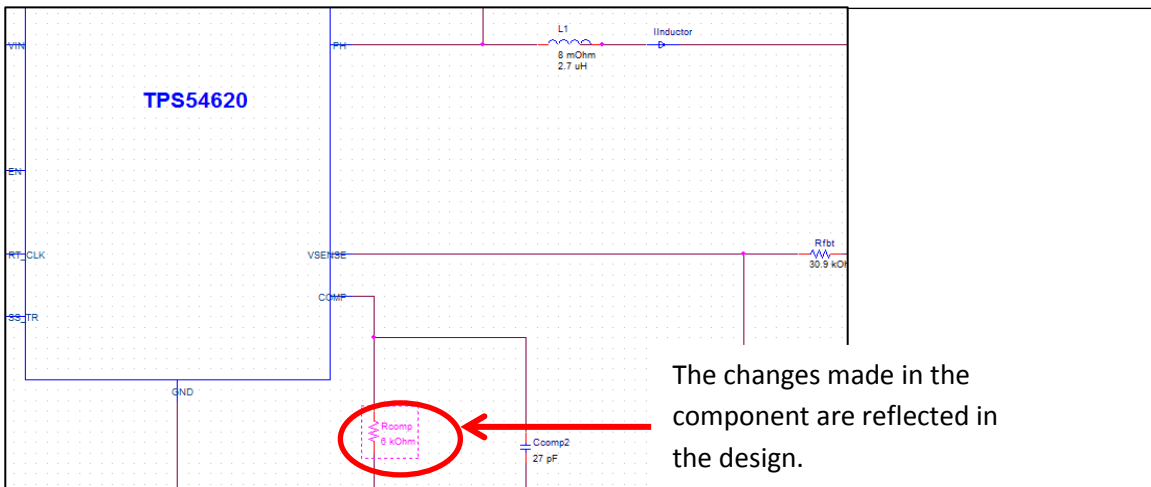
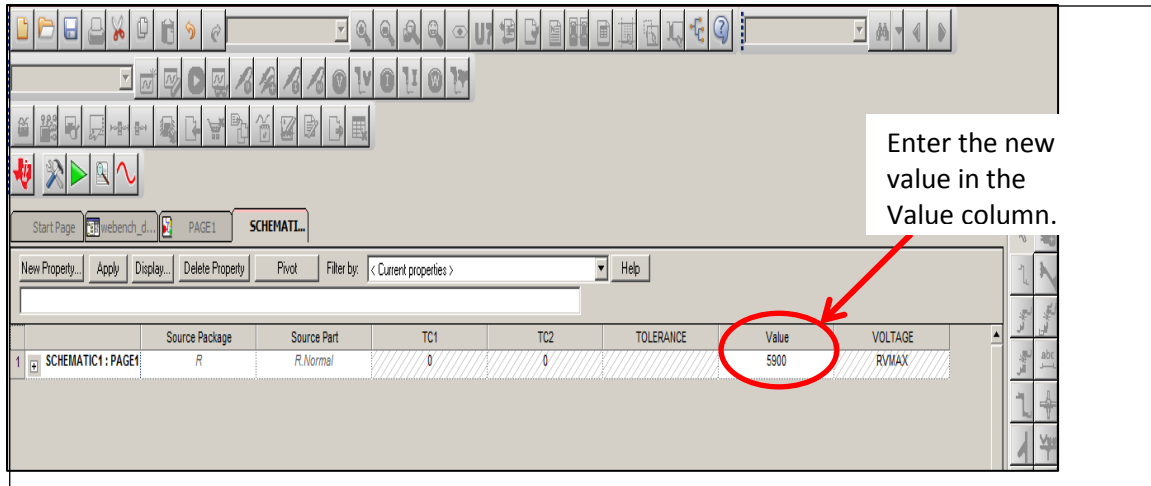


- Upon completion of simulation you can open AMS simulator and open the .dat file in `<project_dir>/*-PspiceFiles/SCHEMATIC1/<Analysis_name>/<Analysis_name>.dat`



- To edit primitive components in OrCAD, double click on the component the you wish to change. . Then change the value to the desired one.





6. Using the integrated circuit macro model

- a. Copy the following files to the project folder. (Project in which you want to use the IC.)
WB_<Part Name>.

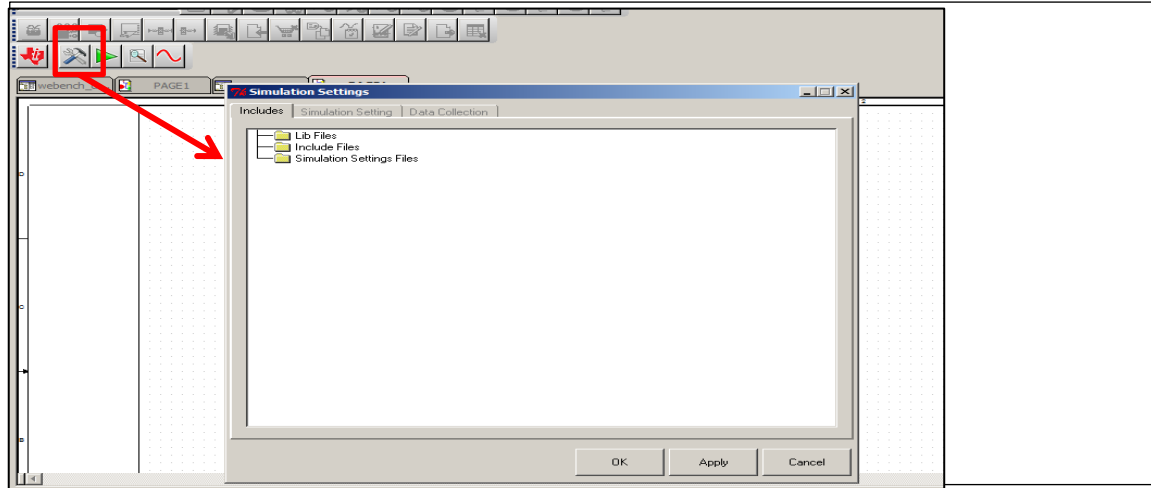
Name	Date modified	Type	Size
webench_design_4211526_942_spb16_sim-PSpiceFiles	27-01-2015 17:43	File folder	
MAIN_BLOCK.U1.WB_TPS54620.enl	27-01-2015 17:43	ENL File	26 KB
MAIN_BLOCK_Cin_WB_CAP_POLARIZED.lib	27-01-2015 17:43	LIB File	1 KB
MAIN_BLOCK_Cout_WB_CAP_CERAMIC.lib	27-01-2015 17:43	LIB File	1 KB
MAIN_BLOCK_L1_WB_INDUCTOR.lib	27-01-2015 17:43	LIB File	1 KB
MAIN_BLOCK_U1.WB_TPS54620.lib	27-01-2015 17:43	LIB File	2 KB
WB_ANALOG.OLB	27-01-2015 17:43	OLB File	9 KB
WB_ANALOG.OLBick	27-01-2015 17:43	OLBLOCK File	16 KB
WB_ANALOG_ob.xml	27-01-2015 17:43	XML Document	18 KB
WB_MISC.OLB	27-01-2015 17:43	OLB File	7 KB
WB_MISC.OLBick	27-01-2015 17:43	OLBLOCK File	16 KB
WB_MISC_ob.xml	27-01-2015 17:43	XML Document	5 KB
WB_SOURCES.OLB	27-01-2015 17:43	OLB File	7 KB
WB_SOURCES.OLBick	27-01-2015 17:43	OLBLOCK File	16 KB
WB_SOURCES_ob.xml	27-01-2015 17:43	XML Document	7 KB
WB_TPS54620.OLB	27-01-2015 17:43	OLB File	8 KB
WB_TPS54620.OLBick	27-01-2015 17:43	OLBLOCK File	16 KB
WB_TPS54620_ob.xml	27-01-2015 17:43	XML Document	19 KB
WEBENCH_DESIGN_4211526_942_SPB16_SIM.DSN	27-01-2015 17:43	Data Source Name	113 KB
WEBENCH_DESIGN_4211526_942_SPB16_SIM.DSNick	27-01-2015 17:43	DSNBLOCK File	16 KB
webench_design_4211526_942_spb16_sim.opj	27-01-2015 17:43	OPJ File	2 KB
webench_design_4211526_942_spb16_sim.tpf	27-01-2015 17:43	TPF File	1 KB
webench_design_4211526_942_spb16_sim.xml	27-01-2015 17:43	XML Document	148 KB
WEBENCH_DESIGN_4211526_942_SPB16_SIM_0.DBK	27-01-2015 17:43	DBK File	43 KB
webench_design_4211526_942_spb16_sim_dsn.xml	27-01-2015 17:43	XML Document	111 KB
webench_design_4211526_942_spb16_sim_import.log	27-01-2015 17:43	LOG File	6 KB

Share with Burn New folder

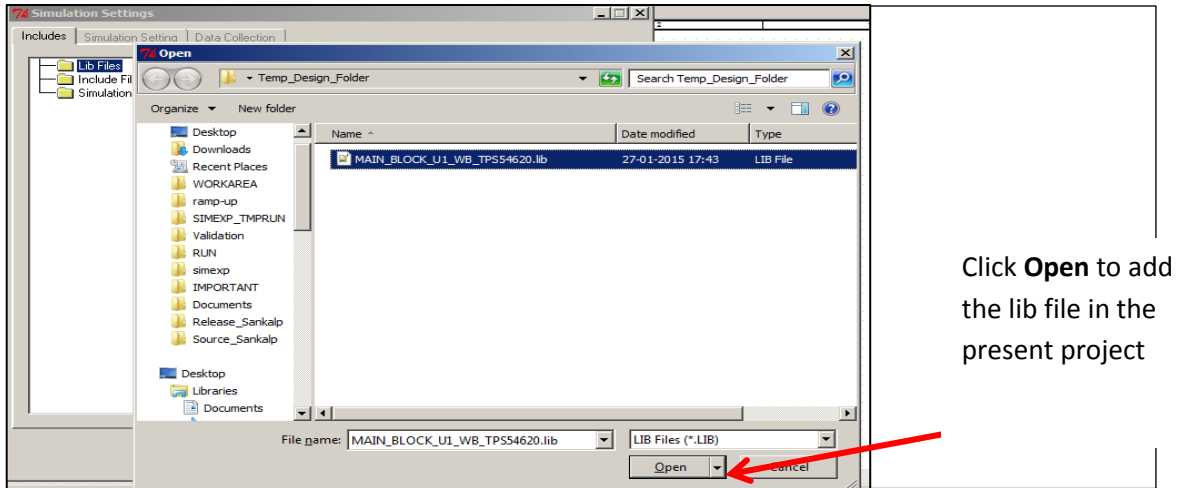
Name	Date modified	Type	Size
MAIN_BLOCK.U1.WB_TPS54620.enl	27-01-2015 17:43	ENL File	26 KB
MAIN_BLOCK_U1.WB_TPS54620.lib	27-01-2015 17:43	LIB File	2 KB
WB_TPS54620.OLB	27-01-2015 17:43	OLB File	8 KB

Copy the above highlighted files in a project folder

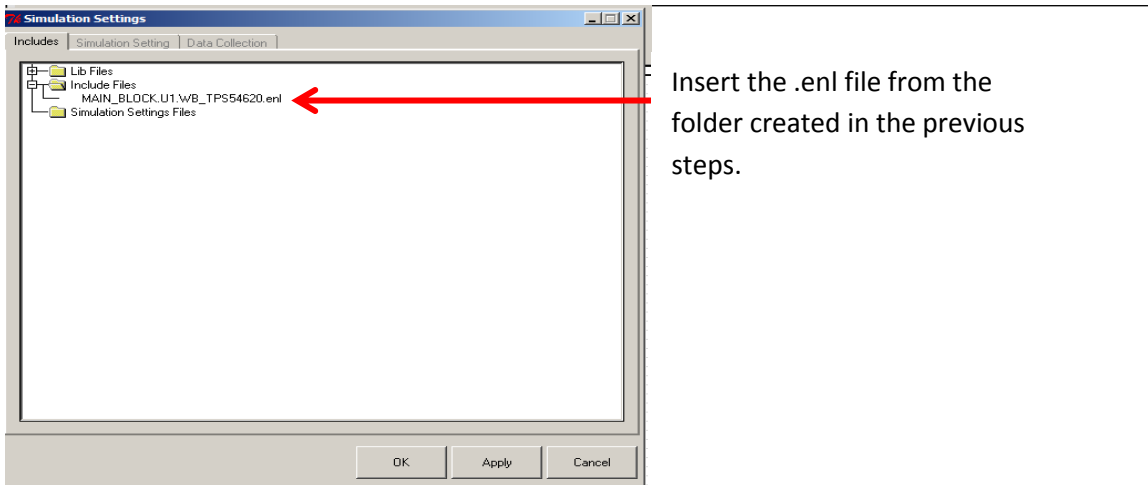
b. Next, open the project in OrCAD where the model is to be reused. Go to simulation settings.



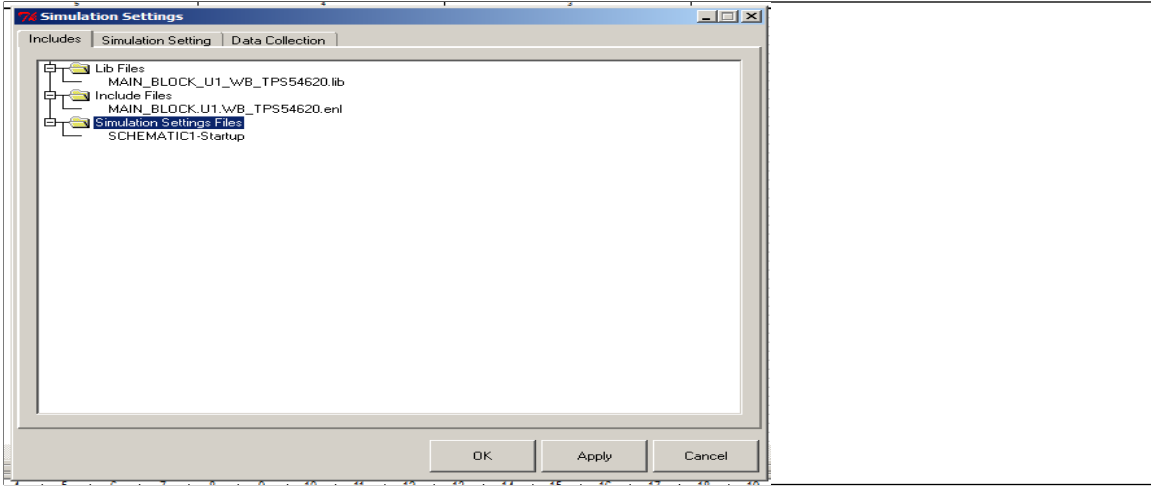
c. Right click the Lib Files and add the lib file which was pasted in the above step.



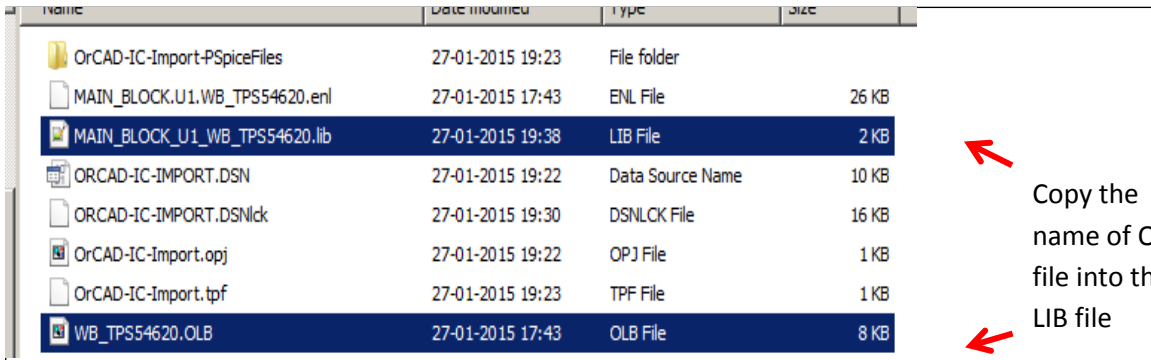
d. Similarly, add the .enl file in Include Files folder



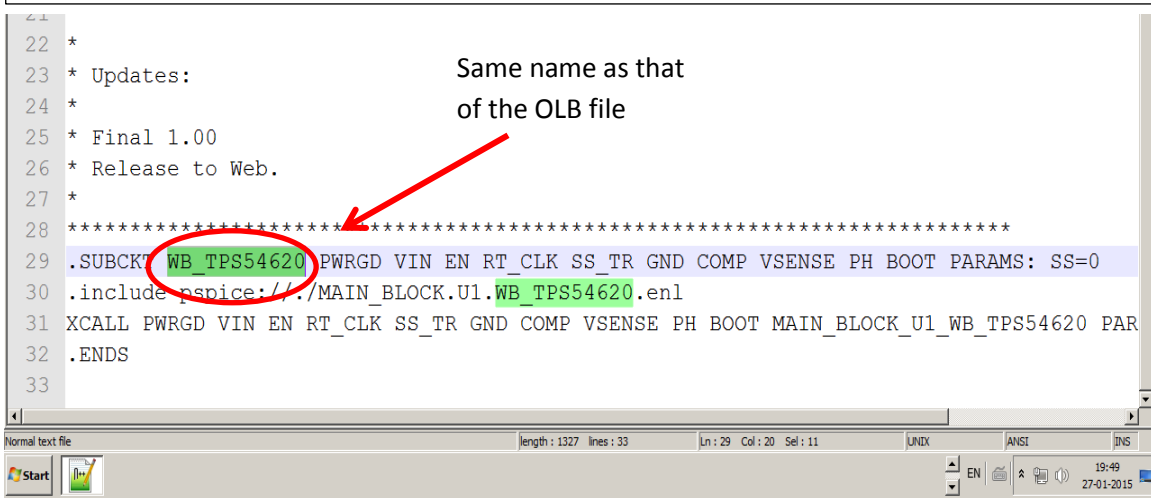
e. Next, right click on **Simulation Settings** , enter the profile name and select **Import from WBSE** and **OK**



f. After making these changes, go to the current project directory and replace the name of the subcircuit in the LIB file to the name of the OLB file.

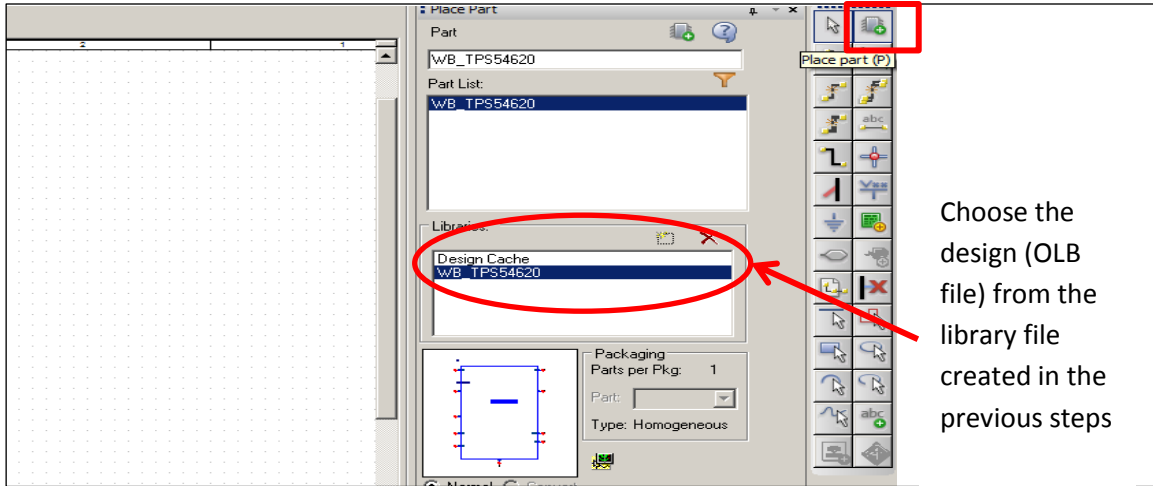


Copy the name of OLB file into the LIB file

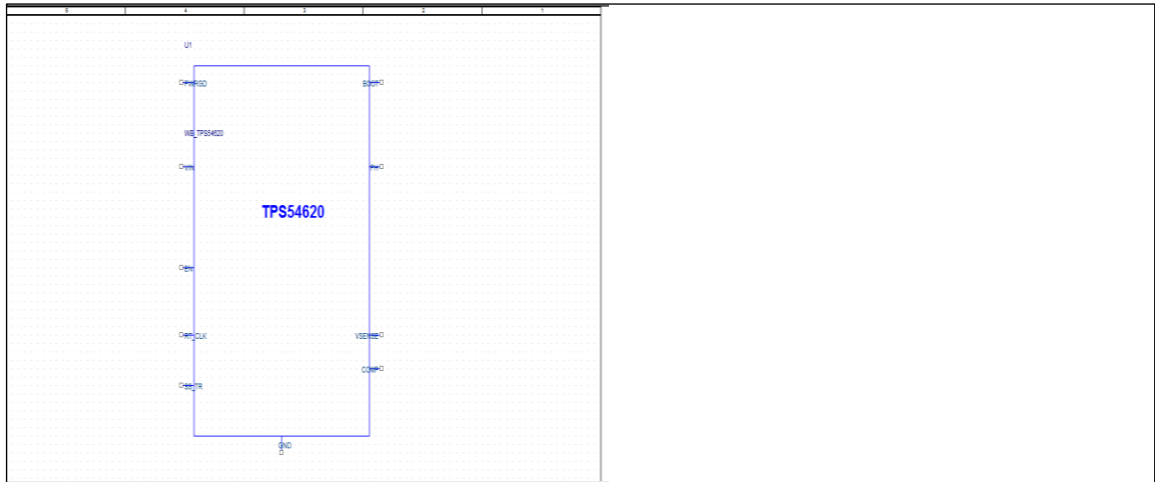


Same name as that of the OLB file

g. Once these changes are made, the next step is to place the part in the schematic editor of OrCAD.



h. The part symbol will now be successfully imported and can be used for simulations.



We have several help resources available [here](#) including [videos](#) showing step- by-step instructions on how to use many of the features.

Feedback

Please submit feedback to the [WEBENCH E2E Community](#).

[See our disclaimer](#)

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